

© 2023 Renesas Electronics Corporation. All rights reserved.



## AGENDA

Time	Торіс	Spokesperson
8:35 – 8:55 PT 17:35 – 17:55 CET	Renesas' Al roadmap & product announcement for IoT/Industrial markets	Sailesh Chittipeddi Executive Vice President and General Manager, Embedded Processing, Digital Power and Signal Chain Solutions Group (EPSG)
8:55 – 9:15 PT 17:55 – 18:15 CET	Next-generation automotive MCU/SoC roadmap	Vivek Bhan Senior Vice President and Co-General Manager, High Performance Computing, Analog and power Solutions Group (HPCSG)
9:15 – 9:30 PT 18:15 – 18:30 CET	Q&A	

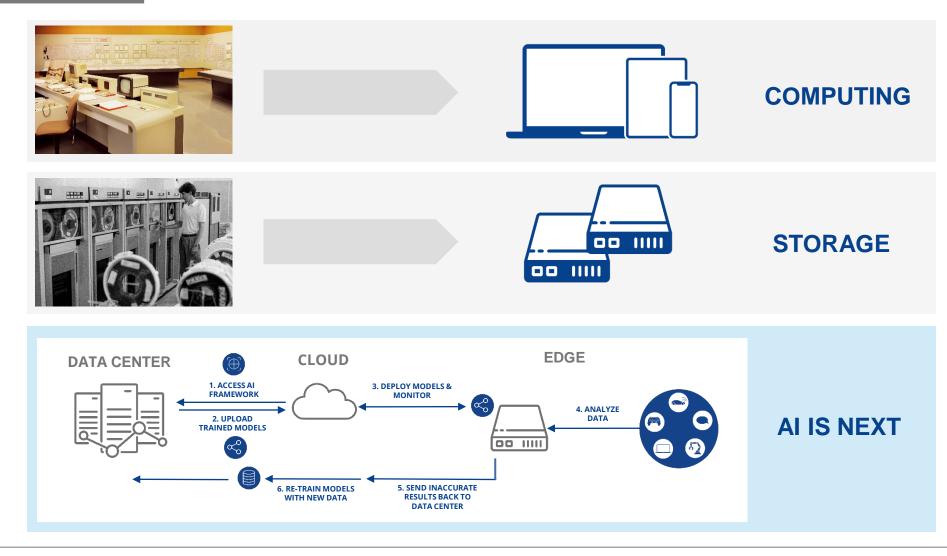
### ARTIFICIAL INTELLIGENCE DISRUPTING IOT FROM INFRA TO EDGE

**DR. SAILESH CHITTIPEDDI** EXECUTIVE VICE PRESIDENT & GENERAL MANAGER EMBEDDED PROCESSING, DIGITAL POWER & SIGNAL CHAIN SOLUTIONS GROUP





# MOVE FROM CENTRALIZED TO DE-CENTRALIZED SYSTEMS

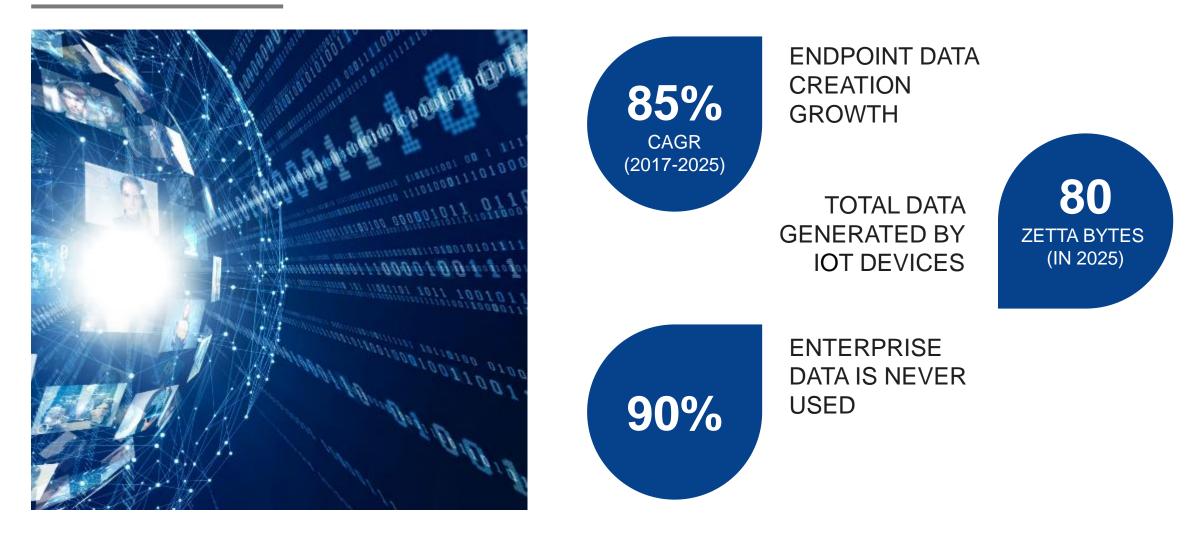




# **GENERATIVE V/S PREDICTIVE AI**

	GENERATIVE AI	PREDICTIVE AI (EDGE)
GOAL	Generate new content Will move to edge in 5+ years	Analyze data to make predictions and business decisions
INPUT	Digital - text (UNICODE), images (jpg, bmp,)	Digitized analog sensor inputs from physical world – 6DOF, environmental (gas), audio, image, video
LEARNING TYPE	Supervised with Reinforcement (Human in the loop)	Supervised, Unsupervised, Reinforcement Learning, Federated Learning
PRIMARY MODELS	Transformers	Convolutional Neural Networks, Random Trees/Forests, k-Means, Clustering, SVM, RNN/LSTM, and Micro-transformers ©
MEMORY REQUIREMENTS	~100s of GB	~kB to ~10 GB
HARDWARE	GPU/TPU in Cloud	Wide variety including MCU, MPU, NPU, FPGA

# **A DATA EXPLOSION**





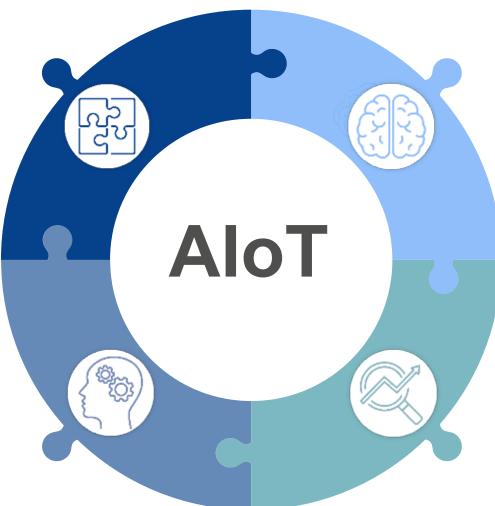
# **A PERFECT ALIGNMENT OF STARS**

### TECHNOLOGY CONVERGENCE

IOT, AI, 5G maturing roughly at the same time



Al transforms data to actionable insights



### DECENTRALIZED INTELLIGENCE

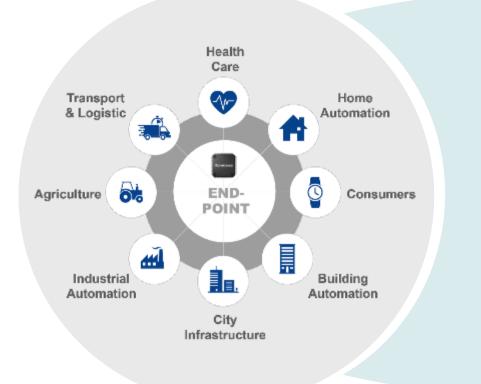
Tremendous benefits of a distributed intelligence model

### DATA EXPLOSION

Endpoint data creation to grow at 85% CAGR (2017-2025)



# **NEW DESIGN MINDSET**



AI/ML Pillars







#### KEY TECHNOLOGIES

- Sensor Fusion
- Motor Control
- HMI
- Wireless Communication
- Capacitive Touch
- Cloud Connectivity
- Functional Safety
- Robotics
- IoT Security

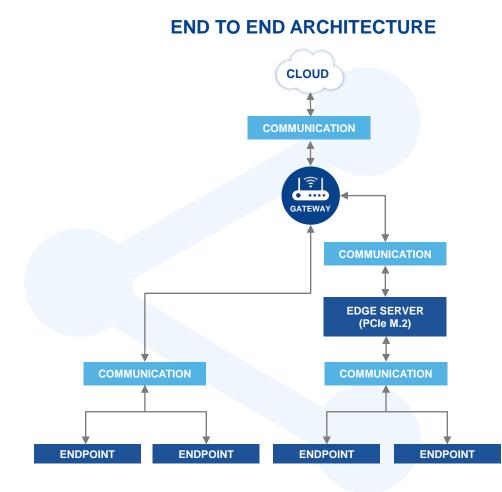
Al/ ML can <u>solve-for or enhance</u> aspects of <u>IOT systems</u> related to <u>maintenance</u>, <u>effectiveness</u>, <u>liability</u>, <u>personalization</u>, <u>service</u>, <u>safety</u>, <u>security</u>, and more

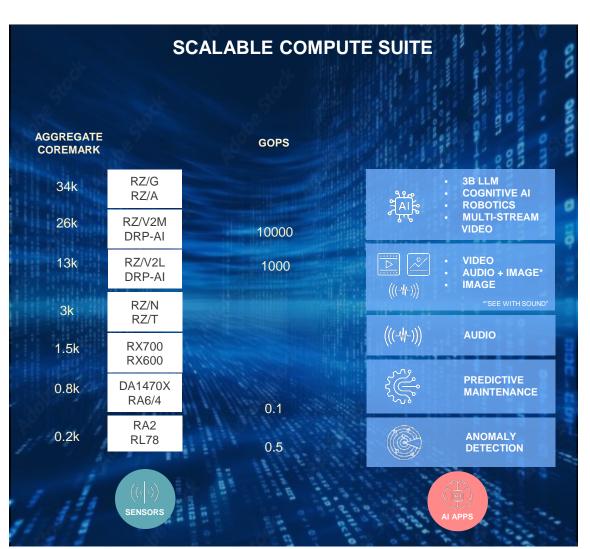
### Al@RENESAS ENABLING INTELLIGENCE FROM THE CLOUD TO THE END-POINT SUSTAINABLY

SOFTWARE PARTNER ECOSYSTEM	RA READY - RA Arm <sup>®</sup> - Cortex <sup>™</sup> -M - MCUs	RX READY • RX 32-Bit • Performance / • Efficiency MCUs		RL78 READY • RL78 Low • Power 8 & 16 - Bit MCUs		RZ READY RZ 32 & 64 - Bit MPUs
AI/ ML APPLICATION ZOO	SOLUTION SUITES	тс	TOOLBOXES APPLICATION EXAMPLES		-	REFERENCE DESIGNS
AI/ML TOOLS & SDKs	<ul> <li>Reality AI Tools</li> </ul>	Reality AI Tools     Reality AI Toolboxes     Reality AI Toolboxes     DRP-A     DRF		V AI SDK NI Translator P-AI TVM Translator		VOICE <ul> <li>Cyberon DSpotter</li> <li>Cyberon Cspotter</li> </ul>
EMBEDDED SOFTWARE & SDKs	<ul> <li>PACKAGES</li> <li>Flexible Software Package (MCU)</li> <li>Firmware Integration Technology (MCU)</li> <li>Software Integration System (MCU)</li> <li>CIP Linux (MPU)</li> </ul>		TOOLS • e <sup>2</sup> studio			
HARDWARE PORTFOLIO	AI AT THE CORE <ul> <li>Timing</li> <li>Power</li> <li>Memory Interface</li> </ul>		AI AT THE EDGE • MPU • Timing • Power • Memory Interface • RF		AI AT THE ENDPOINT MCU/MPU Power Connectivity AMS & CMIC Sensors	



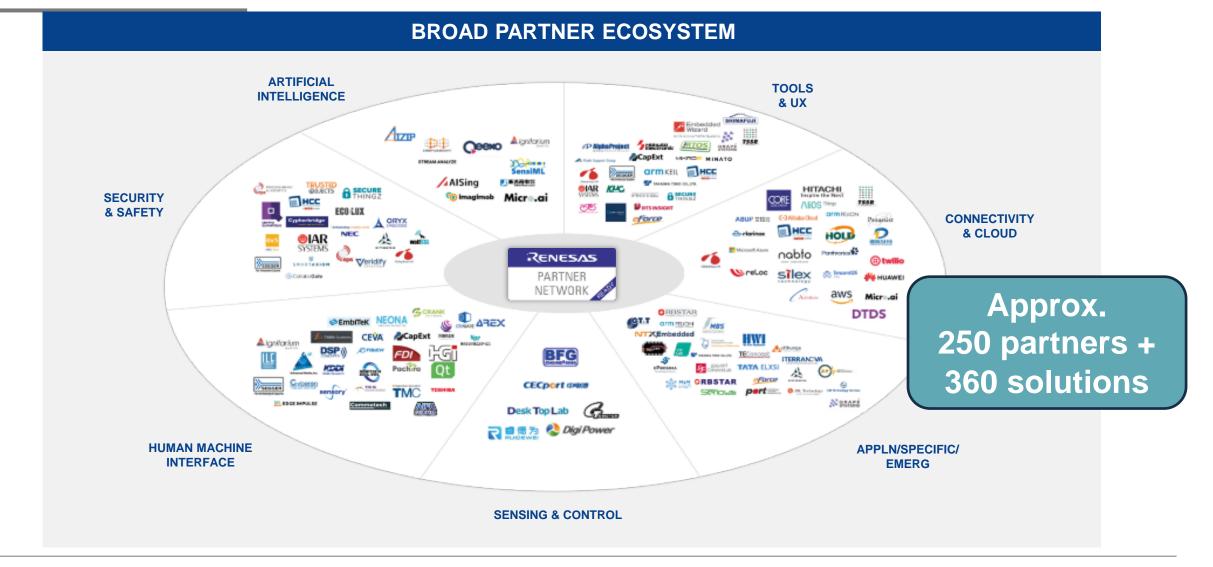
# SCALABLE COMPUTE OFFERINGS





### RENESAS

### AI@RENESAS ENABLING INTELLIGENCE FROM THE CLOUD TO THE END-POINT SUSTAINABLY





# RENESAS RA8 SERIES AND RA8M1 GROUP INTRODUCTION

# RENESAS ELECTRONICS CORPORATION **NOVEMBER 2023** RENESAS RA Arm<sup>®</sup> Cortex<sup>®</sup>-M85 **RA8M1**



# **RENESAS MCU PRODUCT OFFERING**

Meeting various customer needs with multi-architecture CPU product lineup.

8/16bit MCU	32bit MCU			
Renesas Core		Arm <sup>®</sup> Core	RISC-V <sup>®</sup> Core	
RENESAS RL78	RX	RENESAS	RISC-V	
Low Power	Power Efficiency	Arm® Ecosystem	ASSP	
Features:	Features:	Features:	Features:	
Ultra-low energy	Superior power efficiency	High efficiency	Andes RISC-V 32bit CPU	
Low pin count lineup available	High-capacity flash memories	Advanced security	Application specific turnkey solution	
	Broad lineup	Flexible Software Package	1 <sup>st</sup> : Motor control	
Max operating frequency: 20~32MHz	Max operating frequency	Max operating frequency	2 <sup>nd</sup> : Voice recognition	
20~3210172	Max operating frequency: 32~240MHz	Max operating frequency: 48~480MHz	Max operating frequency:	
Application	52~2+010112		32MHz	
General purpose, Sensor, Motor Control	Application	Application		
LCD Display control	General purpose, Security, Motor control	LCD Display control	Application	
Bluetooth® Low Energy	Capacitive touch key,	Network, Wireless	Refrigerator compressor, fan,	
Sub-GHz	LCD Display control	Capacitive touch key	pump control	
Security	Cloud connectivity	Security	Voice command	
	Industrial network	Motor Control		

RENESAS

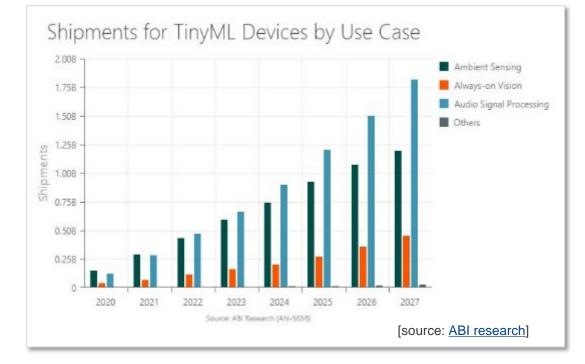
# MARKET TRENDS DRIVE DEMAND FOR HIGHER PERFORMANCE MCUs

#### TRENDS IN THE HIGH PERFORMANCE AND AI MARKETS

- Increased demand for AI on Edge devices drives need for higher performance and ML acceleration
- Increased need for compute capabilities on Edge devices (motor control, drone navigation, robotic arms) requires higher performance and DSP capabilities
- Higher performance MCU-based solutions extend prior investment and avoid having to switch to an MPU
- Advanced security for protection of data at rest or in motion

#### WHY AI ON THE EDGE?

- Drivers for Edge AI (autonomous operation of end point devices)
  - Lower Latency
  - Lower Power Consumption
  - Lower Bandwidth Requirements
  - Lower Cost
  - Better Security



#### INCREASED COMPUTE CAPABILITY AT THE EDGE AND INCREASING AVAILABILITY OF "TINY" ML MODELS FUEL AI CAPABILITY IN EDGE PRODUCTS

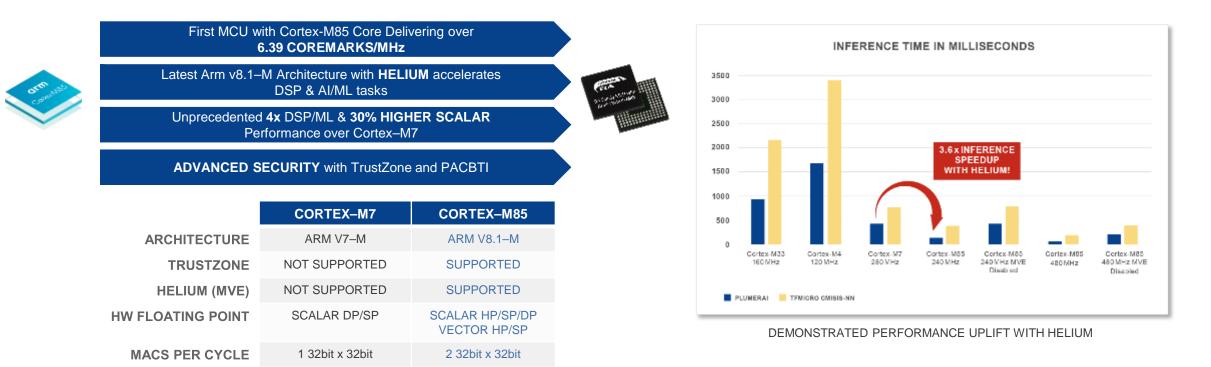


# INDUSTRY'S FIRST MCU WITH NEW ARM CORTEX-M85 CORE!

#### THE NEW RA8 MCUs ...

- Bridge the gap between MCUs and MPUs
- Enable compute-intensive applications with the lower power consumption and ease of use of an MCU

6.39





COREMARKS/MHz

5.29

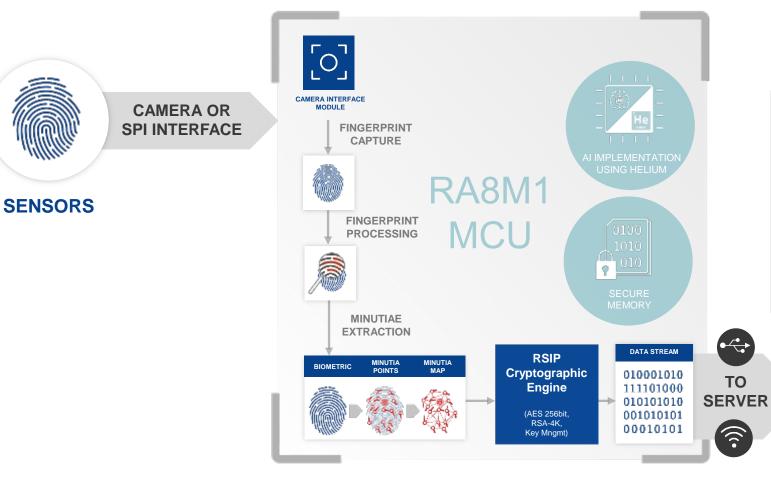
### **TARGET APPLICATIONS**

#### **RA8x1 ARE GENERAL PURPOSE MCUs AND FIND APPLICATION ACROSS BROAD MARKETS**

INDUSTRIAL APPLICATIONS	CONSUMER PRODUCTS	SMART HOME AND BUILDING AUTOMATION	OFFICE AUTOMATION	HEALTHCARE
<ul> <li>PLC</li> <li>Motor Control</li> <li>Power Inverters</li> <li>Industrial HMI</li> <li>Robotics</li> <li>Predictive Maintenance Applications</li> </ul>	<ul> <li>Smart Appliances</li> <li>White Goods</li> <li>Security Cameras</li> <li>Robotic Vacuum Cleaners</li> <li>Exercise Equipment with Display</li> </ul>	<ul> <li>HVAC</li> <li>Safety and Access</li> <li>Security Panels</li> <li>Smart Thermostats</li> <li>Lighting Control</li> <li>Home: Hubs/Gateways</li> </ul>	<ul> <li>Barcode Fingerprint Scanners</li> <li>Scanners</li> <li>Office Equipment with display</li> <li>QR Code readers</li> </ul>	<ul> <li>Patient Monitors</li> <li>Infusion pumps</li> <li>CPAP Machines</li> <li>Respirators</li> <li>Hospital beds</li> </ul>



# **RA8M1 APPLICATION EXAMPLE: FINGERPRINT SCANNER BY MANTRA**



#### **KEY APPLICATION NEEDS**

- High performance and FPU for fingerprint processing algorithms
- Helium for AI implementation
- Large memory size
- Advanced Security: AES 256, RSA-4K key management, secure memory
- Camera or SPI interface for fingerprint acquisition
- Connectivity peripherals

#### **FINGERPRINT SCANNER**



# **SUMMARY & KEY TAKEAWAYS**

- The convergence of AI & IoT is a megatrend that cannot be ignored
- With explosive growth in endpoint data creation a decentralized intelligence architecture will unlock tremendous potential
- Decentralization of intelligence has very real benefits & implications
- Renesas with its comprehensive offering of hardware, software, tools & ecosystem provides all the building blocks for you to unleash your creativity

**RA8 Series** 

- Industry's first 32-bit MCUs based on the new Arm<sup>®</sup> Cortex<sup>®</sup> -M85 core
- Arm Helium technology provides up to 4x DSP and ML performance improvement vs. Cortex M7-based MCU
- Significant increase in performance (>6.3 CoreMark/MHz), bridging the gap between MCUs and MPUs
- Renesas remains committed to advancing AI/ML innovations by addressing rigorous demands of today's endpoint solutions, encompassing performance, latency, real-time response and power.





# RENESAS' NEXT GEN AUTOMOTIVE DIGITAL PRODUCT ROADMAP

NOVEMBER 7, 2023

VIVEK BHAN SENIOR VICE PRESIDENT, CO-GENERAL MANAGER OF HIGH PERFORMANCE COMPUTING, ANALOG AND POWER SOLUTIONS GROUP RENESAS ELECTRONICS CORPORATION



- R-Car Generation 5 (Gen 5) introduction
- R-Car Gen 5 SoC products
- R-Car Gen 5 MCU products



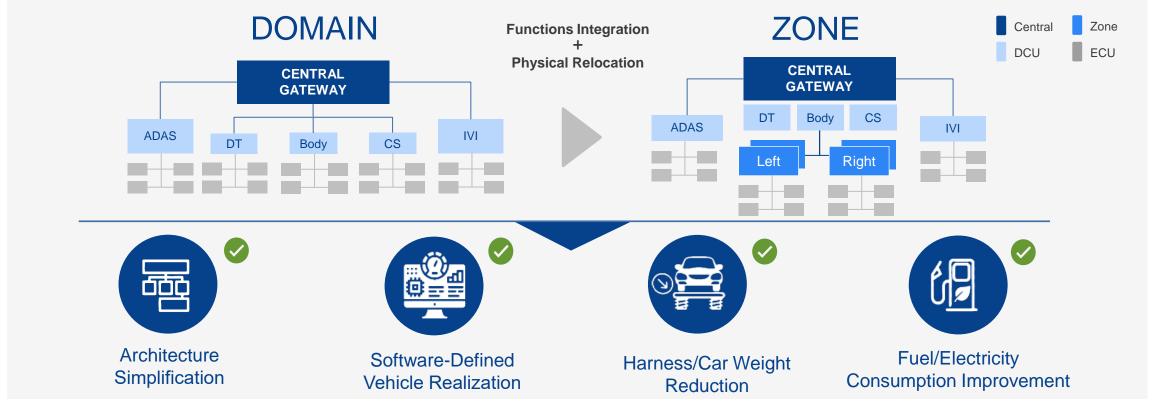
# **R-CAR GEN 5 INTRODUCTION**





# MARKET SHIFT TO CENTRALIZED E/E ARCHITECTURE

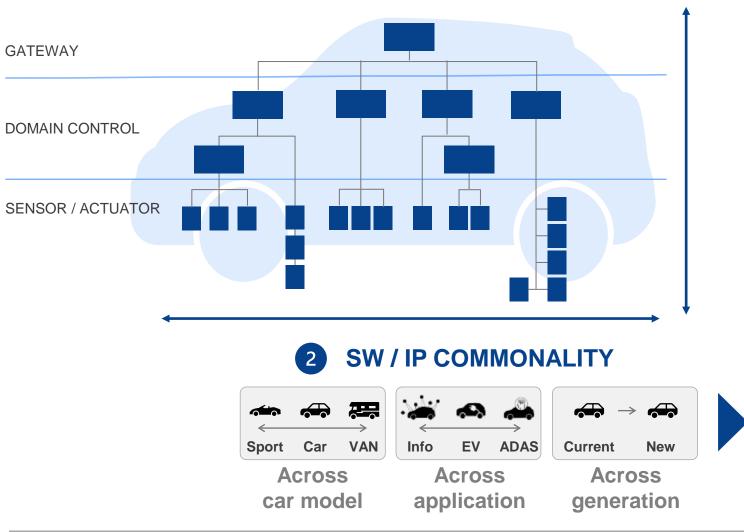
The market demands solutions to address E/E Architecture's shift to Centralized/Zonal Architecture



DCU: Domain Control Unit, ECU: Electronic Control Unit, DT: Drivetrain (Powertrain), CS: Chassis, IVI: In-Vehicle Infotainment,



# **RENESAS VALUE IN E/E ARCHITECTURE**



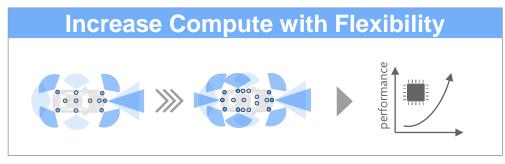
PERFORMANCE SCALING



RENESAS

# MARKET TRENDS AND CUSTOMER PAIN POINTS

### Customer pain points







### **Renesas Initiatives**

#### **Chiplet Architecture**

- Open Compute solutions deployed with industry-standard chiplets
- Modular HW and systems to meet OEM bespoke processing needs

### **Re-Use of Software**

- Common SW framework across MCUs & SoCs
- 100% portability and re-usability across generations: cloud-based AI solutions

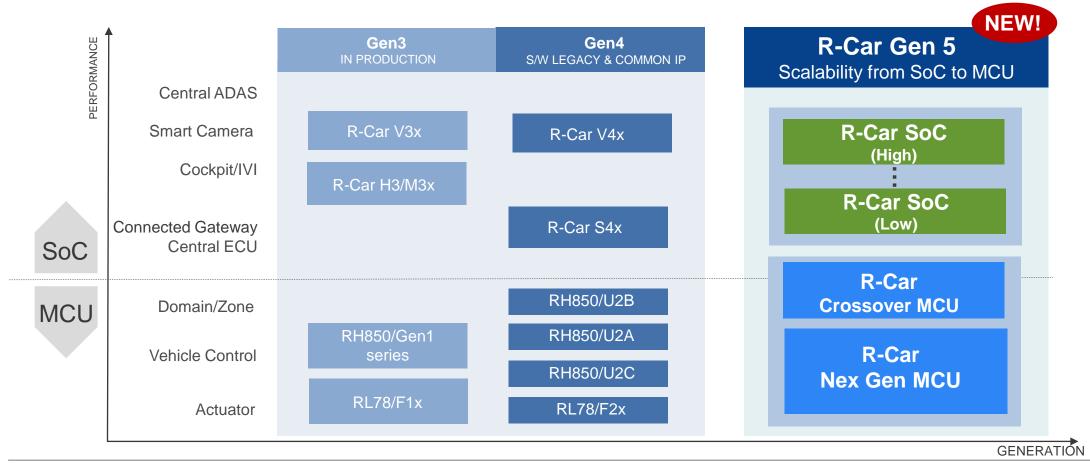
### Shift Left + Cloud Initiatives

- Cloud based SW development for pre and post deployment
- Shift left Software first approach for OTA ready solutions



### R-Car GEN 5 PRODUCT FAMILY – PERFORMANCE & SCALABILITY FOR THE NEXT DECADE

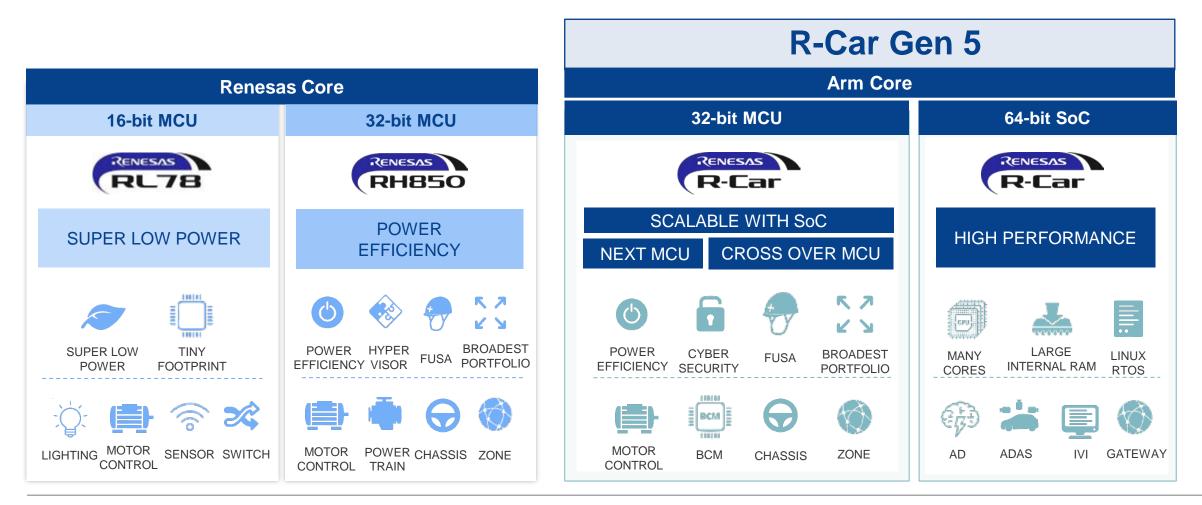
A versatile Arm-based platform offers scalability and flexibility, while allowing for the reuse of software assets across different products and generations.





# RENESAS' ENTIRE AUTOMOTIVE EMBEDDED PROCESSORS

Renesas provides for the various needs of our customers with a rich lineup of automotive MCUs and SoCs.





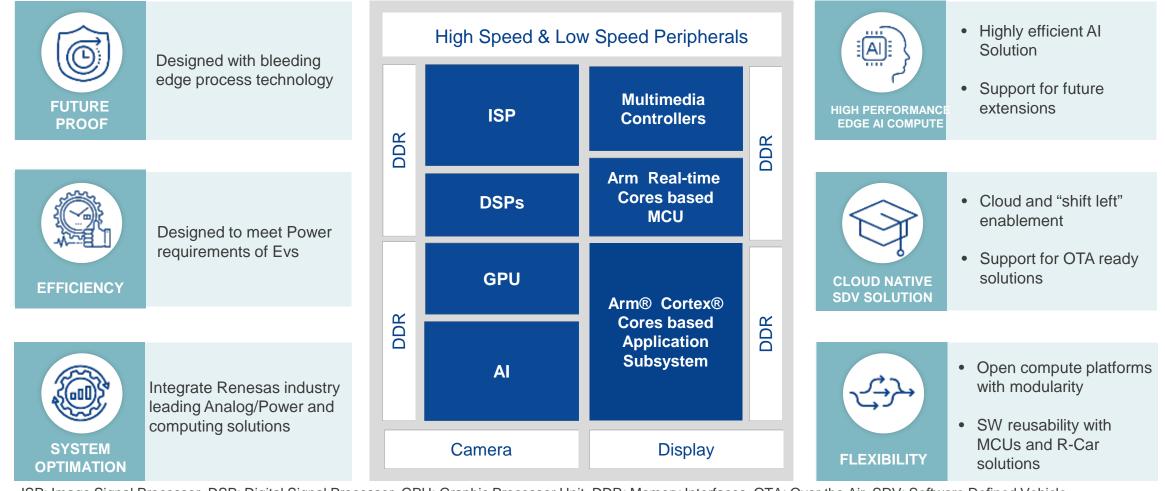
# R-CAR GEN 5 SoC





### R-CAR GEN5 SoC – ARCHITECTED FOR THE SOFTWARE DEFINED VEHICLE (SDV)

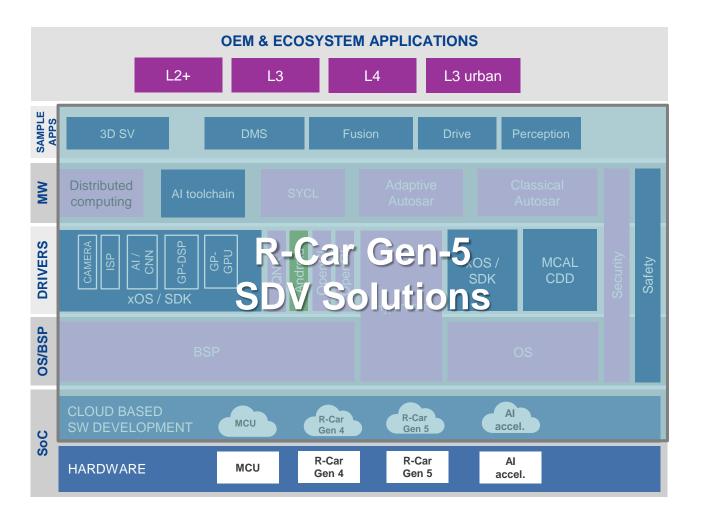
#### **Chiplet Architecture**



ISP: Image Signal Processor, DSP: Digital Signal Processor, GPU: Graphic Processor Unit, DDR: Memory Interfaces, OTA: Over the Air, SDV: Software Defined Vehicle



# **R-CAR GEN 5 SDV ENABLING PLATFORM**



### R-Car Gen 5 Software Defined Vehicle(SDV) Solutions

- «Shift Left» enabled Software solutions

   multi-generation & product family
   support
- Pre-integrated and validated including partners' solutions
- Cloud based development enabling OTA and upgradibility post-deployment



3D SV: 3D Surround View, DMS: Driver Monitoring System, MW: Middle Ware, SDK: Software Development Kit, CDD: Complex Device Driver, BSP: Board Support Package



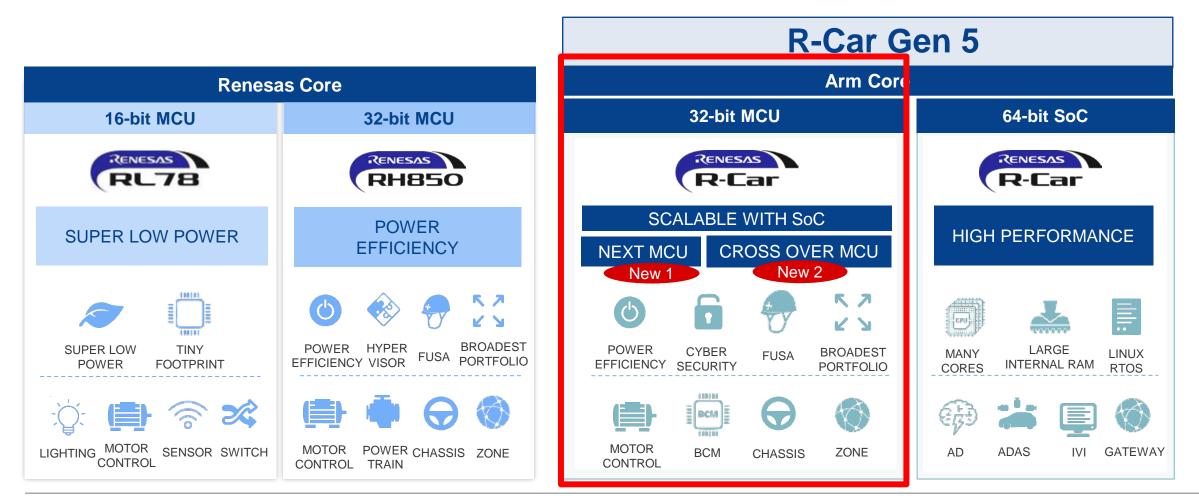
# NEXT GEN MICROCONTROLLERS





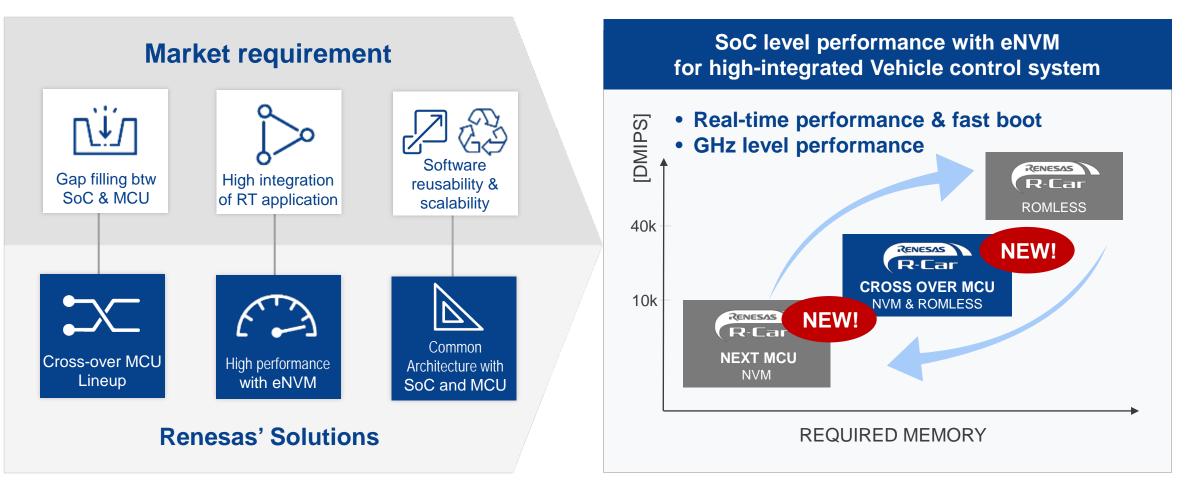
# RENESAS' ENTIRE AUTOMOTIVE EMBEDDED PROCESSORS

Renesas provides for the various needs of our customers with a rich lineup of automotive MCUs and SoCs.





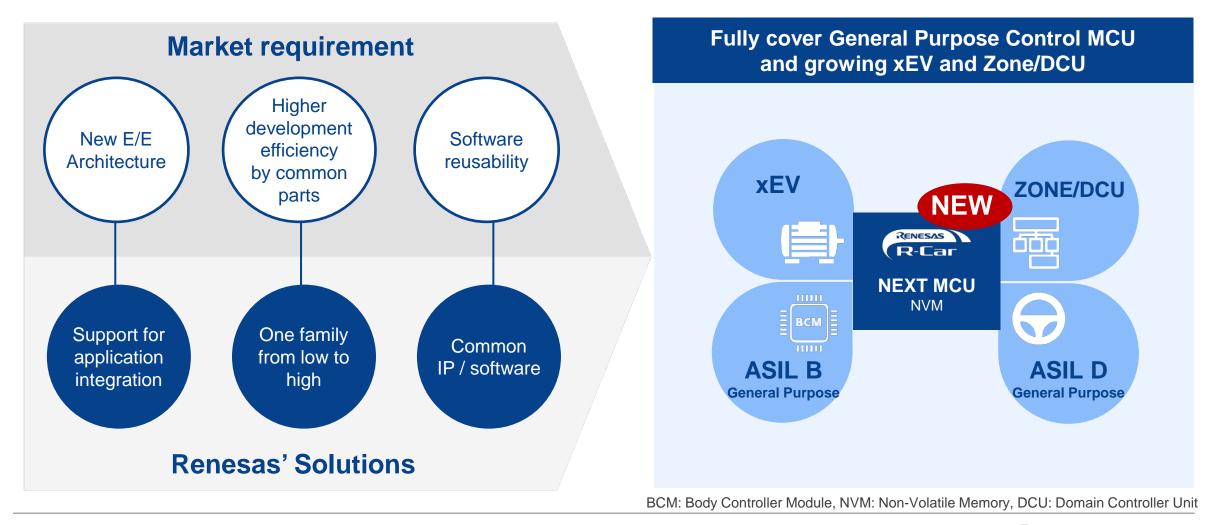
# 1. CROSSOVER MCU ARM FAMILY - CONCEPT



RT: Real Time, eNVM: embedded Non-Volatile Memory



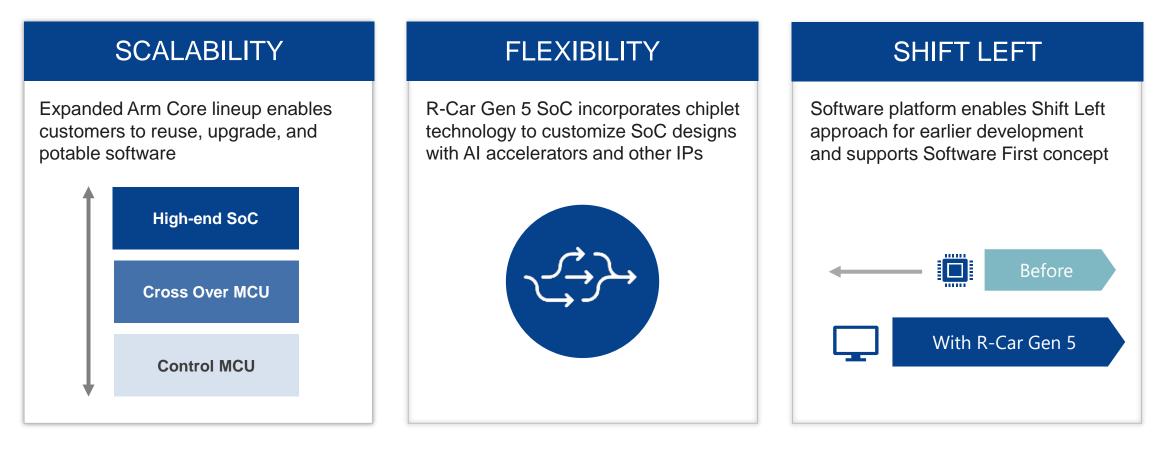
# 2. NEXT-GEN MCU ARM FAMILY - CONCEPT





## SUMMARY OF R-CAR GEN5

Renesas develops R-Car Gen 5 products and SW development environments to enable customers to accelerate development and bring their mobilities to market faster.





# THANK YOU !

# **ANY QUESTIONS?**



© 2023 Renesas Electronics Corporation. All rights reserved.





